

## CELCON<sup>®</sup> LW90FS-K

### **CELCON®**

Celcon® acetal copolymer grade LW90FS-K is a wear resistant medium flow grade containing silicone and a high level of PTFE to give excellent slip and wear resistance properties in demanding applications.

Resin Identification POM-S18 ISO 1043   Part Marking Code >POM-S18 ISO 11469   Rheological properties Met volume-flow rate 8 cm <sup>3</sup> /10min ISO 1133   Temperature 190 °C Load 2.16 kg   Moulding shrinkage, parallel 0.9 % ISO 294.4, 2577   Moulding shrinkage, normal 1.1 % ISO 527.1/-2   Tensile modulus 2100 MPa ISO 527.1/-2   Tensile stress at yield, 50mm/min 44 MPa ISO 527.1/-2   Tensile stress at yield, 50mm/min 17 % ISO 179/140   Charpy motched impact strength, 23°C 61 kJ/m² ISO 179/140   Charpy notched impact strength, 23°C 4 kJ/m² ISO 179/140   Charpy notched impact strength, 23°C 44 kJ/m² ISO 179/140   Charpy notched impact strength, 23°C 44 kJ/m² ISO 179/140   Clip calculated 0.4 <sup>(C)</sup> ISO 179/140 ISO 179/140   Clip calculated 0.4 <sup>(C)</sup> ISO 11357.1/-3 ISO 11357.1/-3   Temperature 0 deflection under load, 1.8 MPa 67 °C ISO 751/-2 ISO 11357.1/-3   Coefficient of linear thermal expansion (CLTE), naralle ISO 11359.1/-2 <th>Product information</th> <th></th> <th></th> <th></th>	Product information			
Melt volume-flow rate   8 cm³/10min   ISO 1133     Temperature   190 °C   2     Load   2.16 kg				
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Load   2.16 kg     Moulding shrinkage, parallel   0.9 %     Moulding shrinkage, normal   1.1 %     Typical mechanical properties   ISO 294.4, 2577     Tensile stress at yield, 50mm/min   44 MPa   ISO 527.1/-2     Tensile stress at yield, 50mm/min   17 %   ISO 527.1/-2     Tensile stress at yield, 50mm/min   17 %   ISO 527.1/-2     Tensile stress at yield, 50mm/min   17 %   ISO 527.1/-2     Flexural modulus   2050 MPa   ISO 527.1/-2     Charpy impact strength, 23°C   4 kJ/m²   ISO 179/1eA     Izod notched impact strength, 23°C   4 kJ/m²   ISO 179/1eA     Izod notched impact strength, 23°C   4 kJ/m²   ISO 178/1A     Poisson's ratio   0.4 <sup>IG</sup> ISO 11357.1/-3     IC): calculated   ISO 11357.1/-3   ISO 11357.1/-3     Thermal properties   ISO 11357.1/-3   ISO 11359.1/-2     Melting temperature of deflection under load, 1.8 MPa   87 °C   ISO 11359.1/-2     (CLTE), parallel   Coefficient of linear thermal expansion   110 E-6/K   ISO 11359.1/-2     Coefficient of linear thermal expansion (CLTE), normal	0 1 1	8	cm <sup>3</sup> /10min	ISO 1133
Moulding shrinkage, parallel   0.9 %   ISO 294-4, 2577     Moulding shrinkage, normal   1.1 %   ISO 294-4, 2577     Typical mechanical properties   2100 MPa   ISO 527-1/-2     Tensile statis at yield, 50mm/min   44 MPa   ISO 527-1/-2     Tensile strain at yield, 50mm/min   17 %   ISO 527-1/-2     Flexural modulus   2050 MPa   ISO 178     Charpy impact strength, 23°C   61 kJ/m²   ISO 179/1eA     Izod notched impact strength, 23°C   4.4 kJ/m²   ISO 179/1eA     Izod notched impact strength, 23°C   4.4 kJ/m²   ISO 179/1eA     Izod notched impact strength, 23°C   4.4 kJ/m²   ISO 180/1A     Poisson's ratio   0.4(°I   ISO 11357-1/-3     [C): Calculated   Thermal properties   ISO 11357-1/-3     Meting temperature, 10°C/min   166 °C   ISO 11357-1/-3     Temperature of deflection under load, 1.8 MPa   87 °C   ISO 11359-1/-2     CoEfficient of linear thermal expansion   110 E-6/K   ISO 11359-1/-2     CoEfficient of linear thermal expansion (CLTE), normal   120 E-6/K   ISO 11359-1/-2     Physical/Other properties   <	•		-	
Moulding shrinkage, normal   1.1 %   ISO 294-4, 2577     Typical mechanical properties   Iso 527-1/-2   Tensile stress at yield, 50mn/min   44 MPa   ISO 527-1/-2     Tensile stress at yield, 50mn/min   17 %   ISO 527-1/-2   Tensile stress at yield, 50mn/min   17 %   ISO 527-1/-2     Tensile stress at yield, 50mn/min   17 %   ISO 527-1/-2   Tensile stress at yield, 50mn/min   17 %   ISO 178/1eU     Charpy impact strength, 23 °C   61 k.//m²   ISO 179/1eU   Charpy impact strength, 23 °C   4 k.//m²   ISO 179/1eA     Izod notched impact strength, 23 °C   4.4 k.//m²   ISO 179/1eA   ISO 179/1eA     Izod notched impact strength, 23 °C   4.4 k.//m²   ISO 180/1A   Poisson's ratio   0.4/GI     [C]: Calculated   ISO 178/1eU   ISO 178/1eU   ISO 11357-1/-3   ISO 11357-1/-3     Temperature of deflection under load, 1.8 MPa   87 °C   ISO 11357-1/-3   ISO 11359-1/-2     Coefficient of linear thermal expansion (CLTE), parallel   ISO 11359-1/-2   ISO 11359-1/-2     Coefficient of linear thermal expansion (CLTE), parallel   ISO 11359-1/-2   ISO 11359-1/-2     Drying Recommended			0	150 204 4 2577
Tensile modulus   2100   MPa   ISO 527-1/-2     Tensile stress at yield, 50mm/min   44   MPa   ISO 527-1/-2     Tensile stress at yield, 50mm/min   17   %   ISO 527-1/-2     Tensile strain at yield, 50mm/min   17   %   ISO 527-1/-2     Tensile strain at yield, 50mm/min   17   %   ISO 527-1/-2     Tensile strain at yield, 50mm/min   17   %   ISO 527-1/-2     Tensile strain at yield, 50mm/min   17   %   ISO 527-1/-2     Flexural modulus   2050   MPa   ISO 178     Charpy inpact strength, 23 °C   4   kJ/m²   ISO 179/1eA     Izod notched impact strength, 23 °C   4 k J/m²   ISO 180/1A   Poisson's ratio   0.4 <sup>(C)</sup> Izod notched impact strength, 23 °C   4 k J/m²   ISO 11357-1/-3   ISO 180/1A   Poisson's ratio   0.4 <sup>(C)</sup> ISO 11357-1/-3     IC: Cic Loulated   10   E-6/K   ISO 11357-1/-2   ISO 11359-1/-2   ISO 11359-1/-2     Coefficient of linear thermal expansion (CLTE), parallel   120   E-6/K   ISO 11359-1/-2     Physical/				
Tensile stress at yield, 50mm/min44MPaISO 527-1/-2Tensile strain at yield, 50mm/min17%ISO 527-1/-2Flexural modulus2050MPaISO 178Charpy impact strength, 23°C61kJ/m²ISO 179/1eUCharpy notched impact strength, 23°C4kJ/m²ISO 179/1eAIzod notched impact strength, 23°C4.4kJ/m²ISO 179/1eAIzod notched impact strength, 23°C4.4kJ/m²ISO 179/1eAIzod notched impact strength, 23°C4.4kJ/m²ISO 180/1APoisson's ratio0.4 <sup>[C]</sup> 0.4 <sup>[C]</sup> ISO 11357-1/-3[C]: calculatedThermal propertiesISO 75.1/-2ISO 75.1/-2Melting temperature of deflection under load, 1.8 MPa87<°C	Typical mechanical properties			
Tensile strain at yield, 50mm/min17 %ISO 527-1/-2Flexural modulus2050 MPaISO 178Charpy impact strength, 23°C61 kJ/m²ISO 179/1eUCharpy notched impact strength, 23°C4 kJ/m²ISO 179/1eAIzod notched impact strength, 23°C4 kJ/m²ISO 180/1APoisson's ratio0.4 <sup>[C]</sup> ISO 11357-1/-3[C]: Calculated166 °CISO 11357-1/-3Thermal propertiesMelting temperature, 10°C/min166 °CISO 11357-1/-3Temperature of deflection under load, 1.8 MPa87 °CISO 11359-1/-2Coefficient of linear thermal expansion110 E-6/KISO 11359-1/-2(CLTE), parallel120 E-6/KISO 11359-1/-2Coefficient of linear thermal expansion (CLTE), anomal120 E-6/KISO 11359-1/-2Physical/Other propertiesDensity1510 kg/m³ISO 1183InjectionDrying Temperature100 °CDrying Time, Dehumidified Dryer3 -4 hProcessing Moisture Content<0.2 %	Tensile modulus	2100	MPa	ISO 527-1/-2
Flexural modulus 2050 MPa ISO 178   Charpy impact strength, 23°C 61 kJ/m² ISO 179/1eU   Charpy notched impact strength, 23°C 4 kJ/m² ISO 179/1eA   Izod notched impact strength, 23°C 4 kJ/m² ISO 179/1eA   Izod notched impact strength, 23°C 4 kJ/m² ISO 180/1A   Poisson's ratio 0.4 <sup>[C]</sup> ISO 180/1A   [C]: Calculated 0.4 <sup>[C]</sup> ISO 11357-1/-3   Thermal properties   Melting temperature, 10°C/min 166 °C ISO 11357-1/-3   Temperature of deflection under load, 1.8 MPa 87 °C ISO 11359-1/-2   CoEfficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2   CLTE), parallel Coefficient of linear thermal expansion (CLTE), normal 120 E-6/K ISO 11359-1/-2   Physical/Other properties   Density 1510 kg/m³ ISO 1183   Injection   Drying Recommended no   Drying Time, Dehumidified Dryer 3 - 4 h   Processing Moisture Content <0.2 %	•			
Charpy impact strength, 23°C 61 kJ/m² ISO 179/1eU   Charpy notched impact strength, 23°C 4 kJ/m² ISO 179/1eA   Izod notched impact strength, 23°C 4.4 kJ/m² ISO 180/1A   Poisson's ratio 0.4 <sup>[C]</sup> ISO 180/1A   [C]: Calculated 0.4 <sup>[C]</sup> ISO 11357-1/-3   Thermal properties ISO 179/1eU ISO 180/1A   Melting temperature of deflection under load, 1.8 MPa 87 °C ISO 11357-1/-3   Temperature of deflection under load, 1.8 MPa 87 °C ISO 11357-1/-2   Coefficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2   Coefficient of linear thermal expansion (CLTE), normal 120 E-6/K ISO 11359-1/-2   Physical/Other properties Density 1510 kg/m³ ISO 1183   Injection no Drying Temperature 100 °C   Drying Time, Dehumidified Dryer 3 - 4 h Processing Moisture Content ≤0.2 %   Melt Temperature 180 °C Max. melt temperature 80 °C   Min. melt temperature 200 °C Screw tangential speed <0.3 m/s	•			
Charpy notched impact strength, 23 °C 4 kJ/m² ISO 179/1eA   Izod notched impact strength, 23 °C 4.4 kJ/m² ISO 180/1A   Poisson's ratio 0.4 <sup>[C]</sup> ISO 180/1A   [C]: Calculated 0.4 <sup>[C]</sup> ISO 11357-1/-3   Thermal properties ISO 179/1eA   Melting temperature, 10 °C/min 166 °C ISO 11357-1/-3   Temperature of deflection under load, 1.8 MPa 87 °C ISO 179/1eA   Coefficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2   C(LTE), parallel ISO 11359-1/-2 ISO 11359-1/-2   Coefficient of linear thermal expansion (CLTE), aprallel ISO 11359-1/-2 ISO 11359-1/-2   Coefficient of linear thermal expansion (CLTE), aprallel ISO 11359-1/-2 ISO 11359-1/-2   Physical/Other properties Density 1510 kg/m³ ISO 1183   Injection Drying Temperature 100 °C Or   Drying Recommended no Drying Time, Dehumidified Dryer 3 - 4 h   Processing Moisture Content <0.2 %				
Izod notched impact strength, 23 °C 4.4 kJ/m² ISO 180/1A   Poisson's ratio 0.4 <sup>[C]</sup> ISO 180/1A   [C]: Calculated ISO 180/1A ISO 180/1A   Thermal properties   Melting temperature, 10 °C/min 166 °C ISO 11357-1/-3   Temperature of deflection under load, 1.8 MPa 87 °C ISO 75-1/-2   Coefficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2   (CLTE), parallel Coefficient of linear thermal expansion (CLTE), normal 120 E-6/K ISO 11359-1/-2   Physical/Other properties   Density 1510 kg/m³ ISO 1183   Injection   Drying Recommended no   Drying Temperature 100 °C   Drying Temperature Optimum 190 °C   Mett Temperature Optimum 190 °C   Min. melt temperature 200 °C   Screw tangential speed <0.3 m/s				
[C]: Calculated Thermal properties Melting temperature, 10 ° C/min 166 ° C ISO 11357-1/-3 Temperature of deflection under load, 1.8 MPa 87 ° C ISO 75-1/-2 Coefficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2 (CLTE), parallel Coefficient of linear thermal expansion (CLTE), 120 E-6/K ISO 11359-1/-2 normal Physical/Other properties Density 1510 kg/m³ ISO 1183 Injection Drying Temperature 100 ° C Drying Time, Dehumidified Dryer 3 - 4 h Processing Moisture Content 50.2 % Melt Temperature 0 ptimum 190 ° C Min. melt temperature 200 ° C Screw tangential speed ≤0.3 m/s Mold Temperature 0 ptimum 100 ° C		4.4	kJ/m <sup>2</sup>	ISO 180/1A
Thermal properties   Melting temperature, 10 ° C/min 166 ° C ISO 11357-1/-3   Temperature of deflection under load, 1.8 MPa 87 ° C ISO 75-1/-2   Coefficient of linear thermal expansion 110 E-6/K ISO 11359-1/-2   (CLTE), parallel ISO 11359-1/-2   Coefficient of linear thermal expansion (CLTE), normal 120 E-6/K ISO 11359-1/-2   Physical/Other properties ISO 11359-1/-2 ISO 11359-1/-2   Density 1510 kg/m³ ISO 1183   Injection   Drying Recommended no   Drying Temperature 100 °C   Drying Time, Dehumidified Dryer 3 - 4 h   Processing Moisture Content ≤0.2 %   Melt Temperature 180 °C   Max. melt temperature 180 °C   Max. melt temperature 200 °C   Screw tangential speed ≤0.3 m/s   Mold Temperature Optimum 100 °C   Min. mould temperature 80 °C		0.4 <sup>[C]</sup>		
Melting temperature, 10 °C/min166 °CISO 11357-1/-3Temperature of deflection under load, 1.8 MPa87 °CISO 75-1/-2Coefficient of linear thermal expansion110 E-6/KISO 11359-1/-2(CLTE), parallelCoefficient of linear thermal expansion (CLTE), normal120 E-6/KISO 11359-1/-2Physical/Other propertiesDensity1510 kg/m³ISO 1183InjectionDrying Recommendedno Drying Temperature100 °CDrying Time, Dehumidified Dryer3 - 4 h90 °CMelt Temperature Optimum190 °C%Min. melt temperature180 °CMax. melt temperature200 °CScrew tangential speed<0.3 m/s	[C]: Calculated			
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## CELCON<sup>®</sup> LW90FS-K

CELCON®

Hold pressure range Back pressure

#### Additional information

Injection molding



60 - 120 MPa 2 MPa

#### Preprocessing

Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

#### Processing

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

#### Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

#### Processing Notes

#### Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

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NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication as a promise or guarantee of specific properties of our groucts. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the

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Page: 3 of 3